



PROCESS CHANGE NOTIFICATION PCN0414

STANDARDIZED EME-G700 MOLD COMPOUND FOR TQFP PACKAGES

Change Description:

Altera will be standardizing on Sumikon EME-G700 series mold compound for the mold compound used in Altera's Thin Quad Flat Pack (TQFP) packages. All TQFP packages assembled at Amkor Korea and ASE Malaysia that are currently assembled with other mold compounds will be standardized on this mold compound.

Reason for Change:

Apart from providing standardization of mold compound within all TQFP packages, the Sumikon EME-G700 series mold compound provides better yield and reliability performance meeting the Pb-free standards.

Products Affected:

All Altera[®] 32, 44, 100, and 144 pin TQFP devices assembled at Amkor Korea and ASE Malaysia will be standardized to this mold compound.

Product Traceability and Transition Dates:

This change will be implemented beginning February 2005. Customers may receive product molded with EME-G700 series mold compound beginning with top mark date code of 0507 or later. Altera maintains a unique ID marking on the units that can be used to trace the mold compound used when required.

Contact:

For more information, please contact your local Altera sales representative or contact whoria@altera.com in the Altera Customer Quality Engineering Department.